

ABSTRACT

Provided is a method of manufacturing an electronic part in which a circuit element (3) is formed on a surface of a ceramic substrate (1) and conductive balls (2) are used as terminals of the electronic part. After the ceramic substrate (1) and the conductive balls (2) are fixed, the ceramic substrate (1) is appropriately divided. For this, the manufacturing method includes: a first step of forming the circuit element(s) (3) on the surface of a large ceramic substrate (1) including division grooves (4) longitudinally and laterally provided on the surface thereof; a second step of fixing the conductive balls (2) to terminal portion of the circuit element(s) (3); and a third step of applying stress to the large ceramic substrate (1) to open the division grooves (4), to divide the substrate (1), and the first, second, and third steps are performed in the stated order. The stress to be applied in the third step is substantially equally applied to large number of conductive balls (2) or no stress is applied to the conductive balls (2).